



Material Content Data Sheet



Sales Product Name		BTS5012-1EKB		Issued		2. August 2018		
MA#		MA001508564						
Package		PG-DSO-14-47		Weight*		150.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.564	2.36	2.36	23649	23649
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		459	
	non noble metal	iron	7439-89-6	1.383	0.92		9180	
wire	non noble metal	copper	7440-50-8	56.175	37.28	38.26	372765	382519
	non noble metal	copper	7440-50-8	0.692	0.46	0.46	4589	4589
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1112
encapsulation	plastics	epoxy resin	-	7.711	5.12		51166	
	inorganic material	silicondioxide	60676-86-0	75.933	50.38	55.61	503877	556155
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16401	16401
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9757	9757
glue	plastics	epoxy resin	-	0.183	0.12		1213	
	noble metal	silver	7440-22-4	0.862	0.57	0.69	5717	6930
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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